

Title (en)

ANISOTROPIC-ELECTROCONDUCTIVE ADHESIVE COMPOSITION, METHOD FOR CONNECTING CIRCUITS USING THE SAME, AND CONNECTED CIRCUIT STRUCTURE THUS OBTAINED

Publication

**EP 0242025 B1 19910529 (EN)**

Application

**EP 87301263 A 19870213**

Priority

- JP 3108886 A 19860214
- JP 4946586 A 19860306

Abstract (en)

[origin: EP0242025A1] Excellent connection of conductors with high reliability can be accomplished by using an adhesive composition or film capable of exhibiting anisotropic-electroconductivity comprising an electrically insulating adhesive component and electroconductive particles each particle comprising a polymeric core material coated with a thin metal layer.

IPC 1-7

**H01B 1/22**; **H01R 4/04**

IPC 8 full level

**H01B 1/22** (2006.01); **H01R 4/04** (2006.01); **H05K 3/32** (2006.01); **H05K 3/36** (2006.01)

CPC (source: EP US)

**H01B 1/22** (2013.01 - EP US); **H01R 4/04** (2013.01 - EP US); **H05K 3/323** (2013.01 - EP US); **H01L 2224/293** (2013.01 - EP US); **H01L 2224/29399** (2013.01 - EP US); **H01L 2224/81903** (2013.01 - EP US); **H01L 2224/83851** (2013.01 - EP US); **H01L 2224/9211** (2013.01 - EP US); **H01L 2924/01019** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H05K 3/361** (2013.01 - EP US); **H05K 2201/0221** (2013.01 - EP US); **H05K 2201/0233** (2013.01 - EP US); **H05K 2201/068** (2013.01 - EP US); **Y10T 29/49194** (2015.01 - EP US)

Cited by

US6956635B2; EP2202755A4; US5235741A; EP0351047A3; US5710612A; US6103551A; EP0372880A3; US5001542A; DE102004005999B4; EP0387066A1; US5843251A; EP0691660A1; US6042894A; EP0303384A3; US5330684A; EP2251910A3; EP2421054A1; EP0413614A3; US5155301A; EP0348561A1; EP1172824A4; EP1780731A1; GB2505035A; GB2505035B; DE102004006000B4; US9758702B2; US7226660B2; US6452280B1; US6787233B1; WO2013178692A1; WO0213205A1; WO0024005A1; WO9301248A1; US8969706B2; US8969707B2; US6404476B1; EP2339695A1

Designated contracting state (EPC)

DE GB IT NL

DOCDB simple family (publication)

**EP 0242025 A1 19871021**; **EP 0242025 B1 19910529**; DE 3770318 D1 19910704; US 4740657 A 19880426

DOCDB simple family (application)

**EP 87301263 A 19870213**; DE 3770318 T 19870213; US 1390487 A 19870212